

**Amendments to the Claims:**

Following is a complete listing of the claims pending in the application, as amended:

1-7. (Canceled)

8. (Currently amended) A planarizing machine, comprising:

a table having a support surface;

a processing pad on the support surface;

a carrier assembly having a head configured to hold a microelectronic workpiece and a drive assembly carrying the head relative to the support surface; and

a solution dispenser separate from the head, the solution dispenser being configured to discharge a planarizing solution onto a plurality of locations on the pad, wherein the solution dispenser comprises a support extending over the pad at a location spaced apart from a travel path of the head, a fluid passageway carried by the support through which a planarizing solution can flow, and a nozzle carried by the support and in fluid communication with the fluid passageway, the nozzle being rotatably coupled to the support to be movable between a first position to discharge the planarizing solution onto a surface of the pad at a first angle relative to thea surface of the pad and a second position to discharge the planarizing solution at a second angle relative to the surface of the pad, the second angle being different from the first angle.

9-18. (Canceled)

19. (Currently amended) A planarizing machine, comprising:

a table having a support surface;

a processing pad on the support surface;

a carrier assembly having a head configured to hold a microelectronic workpiece and a drive assembly carrying the head; and

a solution dispenser separate from the head, the solution dispenser having a support extending over the pad and a distributor carried by the support, the distributor being configured to discharge a planarizing solution from a plurality of locations along the support, wherein the support comprises an elongated arm and a fluid passageway carried by the arm through which a planarizing solution can flow, and the distributor further comprises a nozzle carried by the arm and in fluid communication with the fluid passageway, the nozzle being rotatably coupled to the arm to be movable between a first position to discharge the planarizing solution onto a surface of the pad at a first angle relative to thea surface of the pad and a second position to discharge the planarizing solution at a second angle relative to the surface of the pad, the second angle being different from the first angle.

20. (Canceled)

21. (Canceled)

22. (Currently Amended) The planarizing machine, comprising:

a table having a support surface;

a processing pad on the support surface;

a carrier assembly having a head configured to hold a microelectronic workpiece and a drive assembly carrying the head; and

a solution dispenser having support above the pad and a nozzle moveably coupled to the support so that the nozzle is movable during a planarizing cycle, the nozzle being coupleable to a planarizing solution, wherein:

the support comprises an elongated arm and a fluid passageway carried by the arm through which a planarizing solution can flow; and

the nozzle is rotatably coupled to the arm to be movable between a first position to discharge the planarizing solution onto a surface of the pad at a first angle relative to thea surface of the pad and a second position to discharge the planarizing

solution at a second angle relative to the surface of the pad, the second angle being different from the first angle.

23-53. (Canceled)

54. (Currently Amended) A method of processing a microelectronic workpiece, comprising:

removing material from the workpiece by pressing the workpiece against a contact surface of a processing pad and imparting relative motion between the workpiece and the contact surface; and

discharging a planarizing solution directly onto a first region of the contact surface and concurrently discharging the planarizing solution directly onto a second region of the contact surface separate from the first region, the planarizing solution being deposited onto the first and second regions separate from a head carrying the workpiece, wherein discharging the planarizing solution comprises (a) passing the planarizing solution through a fluid discharge unit that is moveably carried by a support over the processing pad and (b) concurrently moving the fluid discharge unit relative to the support to discharge the planarizing fluid at different regions across the contact surface while removing material from the workpiece, and wherein the fluid discharge unit includes a nozzle, and further wherein moving the fluid discharge unit comprises rotating the fluid discharge unit about a pivot point on the support, the fluid discharge unit being pivotally movable between a first position to discharge the planarizing solution onto a surface of the pad at a first angle relative to thea surface of the pad and a second position to discharge the planarizing solution at a second angle relative to the surface of the pad, the second angle being different from the first angle.

55. (Canceled)

56. (Canceled)

57. (Previously presented) The planarizing machine of claim 8, further comprising an actuator coupled to the nozzle and configured to rotate the nozzle relative to the support.

58. (Canceled)

59. (Previously presented) The planarizing machine of claim 19, further comprising an actuator coupled to the nozzle and configured to rotate the nozzle relative to the arm.

60. (Canceled)

61. (Canceled)

62. (New) The planarizing machine of claim 8 wherein the support extending over the pad includes at least a portion of the support being positioned over the pad within the lateral confines of the surface of the pad.

63. (New) The planarizing machine of claim 8 wherein the first angle relative to the surface of the pad includes a first angular measurement between the surface of the pad and the planarizing solution discharged from the nozzle when the nozzle is in the first position and the second angle relative to the surface of the pad includes a second angular measurement between the surface of the pad and the planarizing solution discharged from the nozzle when the nozzle is in the second position.

64. (New) The planarizing machine of claim 8 wherein the nozzle includes a first nozzle and wherein the fluid dispenser includes a second nozzle carried by the support and in fluid communication with the fluid passageway, the second nozzle being rotatably coupled to the support to be movable between a first position to discharge the planarizing solution onto the surface of the pad at a third angle relative to the surface of the pad and a second position to discharge the planarizing solution at a fourth angle relative to the surface of the pad, the third angle being different from the fourth angle.

65. (New) The planarizing machine of claim 8 wherein the nozzle is configured to be translatable along the support.

66. (New) The planarizing machine of claim 19 wherein the support extending over the pad includes at least a portion of the support being positioned over the pad within the lateral confines of the surface of the pad.

67. (New) The planarizing machine of claim 19 wherein the first angle relative to the surface of the pad includes a first angular measurement between the surface of the pad and the planarizing solution discharged from the nozzle when the nozzle is in the first position and the second angle relative to the surface of the pad includes a second angular measurement between the surface of the pad and the planarizing solution discharged from the nozzle when the nozzle is in the second position.

68. (New) The planarizing machine of claim 19 wherein the nozzle includes a first nozzle and wherein the distributor includes a second nozzle carried by the arm and in fluid communication with the fluid passageway, the second nozzle being rotatably coupled to the arm to be movable between a first position to discharge the planarizing solution onto a surface of the pad at a third angle relative to the surface of the pad and a second position to discharge the planarizing solution at a fourth angle relative to the surface of the pad, the third angle being different from the fourth angle.

69. (New) The planarizing machine of claim 19 wherein the nozzle is configured to be translatable along arm.

70. (New) The planarizing machine of claim 22 wherein at least a portion of the elongated arm is positioned over the pad within the lateral confines of the surface of the pad.

71. (New) The planarizing machine of claim 22 wherein the first angle relative to the surface of the pad includes a first angular measurement between the surface of the pad and the

planarizing solution discharged from the nozzle when the nozzle is in the first position and the second angle relative to the surface of the pad includes a second angular measurement between the surface of the pad and the planarizing solution discharged from the nozzle when the nozzle is in the second position.

72. (New) The planarizing machine of claim 22 wherein the nozzle includes a first nozzle and wherein the solution dispenser includes a second nozzle distributor includes a second nozzle moveably coupled to the support so that the second nozzle is movable during the planarizing cycle, the second nozzle being coupleable to the planarizing solution wherein the second nozzle is rotatably coupled to the arm to be movable between a first position to discharge the planarizing solution onto a surface of the pad at a third angle relative to the surface of the pad and a second position to discharge the planarizing solution at a fourth angle relative to the surface of the pad, the third angle being different from the fourth angle.

73. (New) The planarizing machine of claim 22 wherein the nozzle is configured to be translatable along the support.

74. (New) The method of claim 54 wherein a support over the pad includes at least a portion of the support being positioned over the pad within the lateral confines of the surface of the pad.

75. (New) The method of claim 54 wherein the first angle relative to the surface of the pad includes a first angular measurement between the surface of the pad and the planarizing solution discharged from the nozzle when the nozzle is in the first position and the second angle relative to the surface of the pad includes a second angular measurement between the surface of the pad and the planarizing solution discharged from the nozzle when the nozzle is in the second position.

76. (New) The method of claim 54 wherein the fluid discharge unit includes a first fluid discharge unit and the nozzle includes a first nozzle, and wherein discharging the

planarizing solution further comprises (a) passing the planarizing solution through a second fluid discharge unit that is moveably carried by the support over the processing pad and (b) concurrently moving the second fluid discharge unit relative to the support to discharge the planarizing fluid at different regions across the contact surface while removing material from the workpiece, and wherein the second fluid discharge unit includes a second nozzle, and further wherein moving the second fluid discharge unit comprises rotating the second fluid discharge unit about a pivot point on the support, the second fluid discharge unit being pivotally movable between a first position to discharge the planarizing solution onto a surface of the pad at a third angle relative to the surface of the pad and a second position to discharge the planarizing solution at a fourth angle relative to the surface of the pad, the third angle being different from the fourth angle.

77. (New) The method of claim 54 wherein moving the fluid discharge unit further includes translating the fluid discharge unit along the support.